



Thermal Pad

High Performance Thermal Pad

- Perfect gap filler
- Particularly suitable to cool several modules
- Protection for sensitive processor chips
- Very simple application
- Non-conducting
- Non-capacitive

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The ARCTIC **Thermal Pad** provides an efficient thermal interface between heat sinks and electronic devices where uneven surface topography, air gaps and rough surface textures are present.

The silicon based material outperforms generic pads by far, is flexible and adaptive and thus works also at low pressure.

Specifications

Dimensions	50 x 50 mm, 120 x 20 mm, 145 x 145 mm, 290 x 290 mm
Thickness	0.5 mm or 1.0 mm or 1.5 mm
Thermal Conductivity	6.0 W/mK
Hardness	50 Shore 00
Specific Gravity	3.2 g/cm ³
Colour	Blue
Continuous Use Temperature	-40~200 °C
Volume resistance	1 X 10 ¹² Ω·cm
Breakdown Voltage	12 KV/mm
Tensile strength	2.5 Kgf/cm ²
Elongation	45 %
Dielectric constant	14.1816 ε at 60 Hz 13.0264 ε at 1K Hz 13.0264 ε at 1M Hz
UL Flammability	V-0

